

客户 CUSTOMER: \_\_\_\_\_

日期 DATE: \_\_\_\_\_

# 纳入仕様书 SPECIFICATION

产品名称 PRODUCT NAME: 叠层片式双工器

Multilayer Chip Diplexer

贵司料号 YOUR PART NO.:

敝司料号 OUR PART NO.: MDPX15M2455P69-D16

版本号 VERSION.: V2.0

接受 RECEPTION

THE SPECIFICATION HAS BEEN ACCEPTED.

该纳入仕様书已被我司接受

日期:  
DATE:

公司:  
COMPANY:

批准

CFMD

审核

CHKD

接收

RCVD

本纳入仕様书共 8 页

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纳入仕様书改定履历 MODIFY HISTORY OF SPECIFICATION

Ver.	DATE	CONTENT	APPROVED
1.0	2019.06.23	初稿 Constitute	梁启新
1.1	2019.08.26	更新焊盘封装规格 Modify the Appearance of Electrode	梁启新
2.0	2020.12.09	更新低频电性参数，并增加包装信息 Modify LB Electrical Characteristics and Add Packaging	付迎华

## 目录 CATALOG

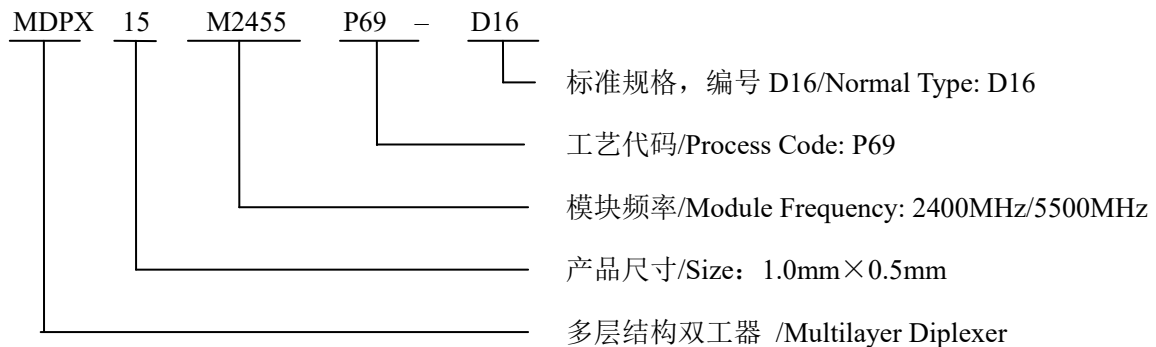
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## 1 适用范围 Scope

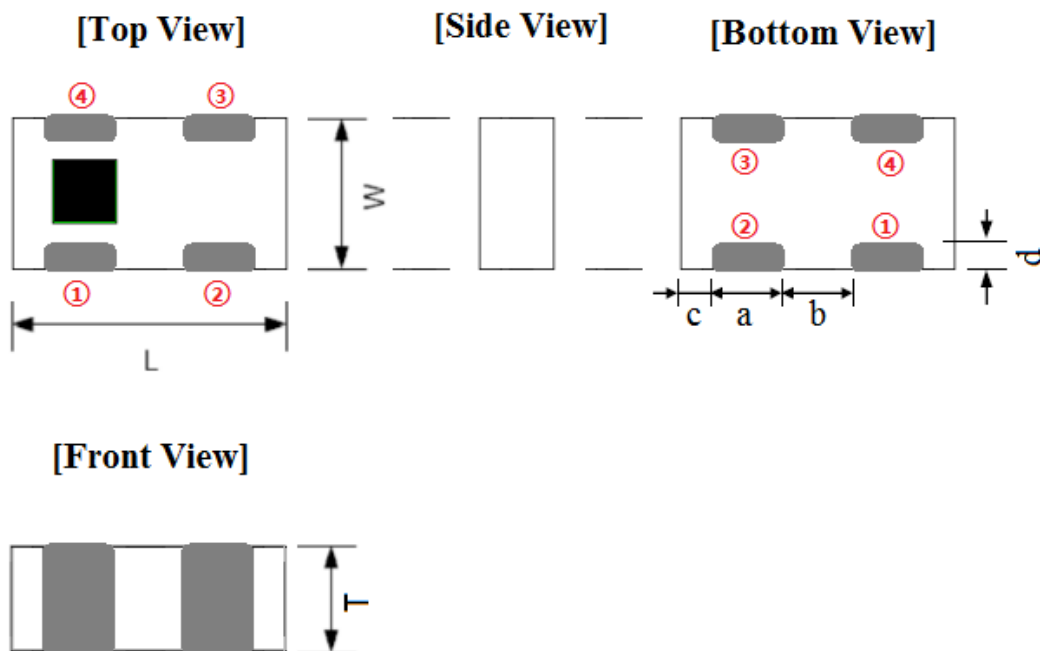
“麦捷”叠层片式双工器系列产品设计用于 5G、LTE、WIFI、Bluetooth、PDA 和无绳电话机等，具有低的插入损耗、高的隔离度和小体积 SMD 片式设计，能减少复杂的调校工作，可以简化电路设计。

“Microgate” Multilayer Chip Diplexer series are designed to be used in 5G、LTE、WIFI、Bluetooth、PDA & cordless phones with low insertion loss and high isolation as well as small size SMD chip design , which can simplify your complex tuning and circuit design .

## 2 品名构成 Product Identification



## 3 形状、尺寸和材料 Appearance, Dimensions and Material



### PIN Configuration

①	②	③	④
Common Port	GND	High-Band	Low-Band

Unit: mm

### Dimension

L	W	T	a	b	c	d
1.0±0.1	0.5±0.1	0.40 Max	0.3±0.1	0.2±0.1	0.10±0.1	0.15±0.05

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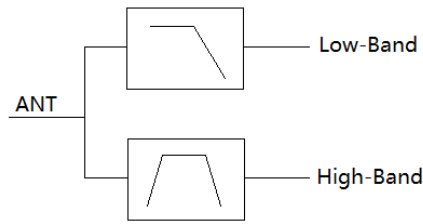
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Circuit Diagram



#### 4 测试条件 Testing Conditions

除非另有规定，否则在以下条件下测试 <Unless otherwise specified>

温度 Temperature : Ordinary Temperature (-40 to +85°C)

湿度 Humidity : Ordinary Humidity (25 to 85% RH)

大气压强 Atmospheric Pressure : 86 to 106 kPa

#### 5 电气性能 Electrical Characteristics

操作温度范围 Operating Temperature Range : -40 to +85°C

保存温度范围 Storage Temperature Range : -40 to +85°C

No.	Item (项目)		Specifications (特性)
5.1	Frequency Range 频率范围 f1		2400~2500 MHz
	Frequency Range 频率范围 f2		4900~5950 MHz
5.2	Insertion Loss (in f1) 插入损耗		≤0.6dB@ +25°C
			≤0.7dB@-40 to +85°C
5.3	Insertion Loss (in f2) 插入损耗		≤0.8dB@ +25°C
			≤1.0dB@-40 to +85°C
5.4	V.S.W.R (in BW) 驻波比 (in f1 & f2)		≤2.0
5.5	Attenuation 阻带衰耗 (in f1)		≥23dB (4800~6000MHz) ≥21dB (7200~7500MHz)
5.6	Attenuation 阻带衰耗 (in f2)		≥25dB (30~2400MHz) ≥32dB (2400~2500MHz) ≥23dB (2500~2690MHz) ≥20dB (9800~11900MHz)
5.7	Isolation 隔离度	HB to LB	≥25dB (2400~2500MHz)
		LB to HB	≥23dB (4900~5950MHz)
5.8	In/Output Impedance 输入/输出阻抗		50 Ω
5.9	Power Capacity		3W Max.

## 6 焊接条件 Recommended Soldering Conditions

### 1、焊剂 Flux, Solder

① 使用松香助焊剂，禁止使用卤化物含量超过 0.2wt% 的强酸性助焊剂。

Use rosin-based flux. Don't use highly acidic flux with halide content exceeding 0.2wt% (chlorine conversion value).

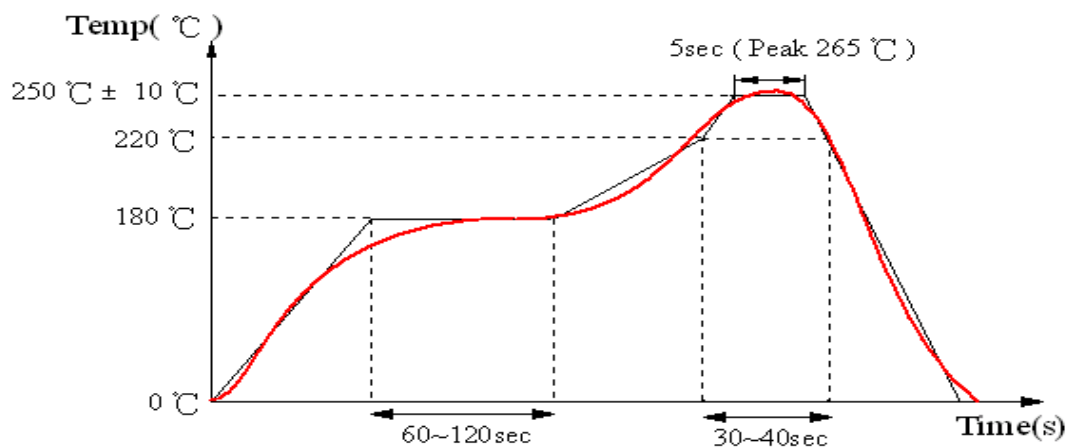
② 使用纯锡焊料 Use Sn solder.

### 2、回流焊条件 Reflow soldering conditions

● 预热时，产品表温与焊料温度的温差最大不允许超出 150℃，焊接完后冷却时，产品表温与溶剂温度之间的温差最大不允许超出 100℃。预热不足有可能引发产品表面裂纹，导致产品品质下降。

Pre-heating should be in such a way that the temperature difference between solder and product surface is limited to 150℃ max. Cooling into solvent after soldering also should be in such a way that temperature difference is limited to 100℃ max. Unwrought pre-heating may cause cracks on the product, resulting in the deterioration of products quality.

● 标准回流焊曲线 Standard soldering profile.



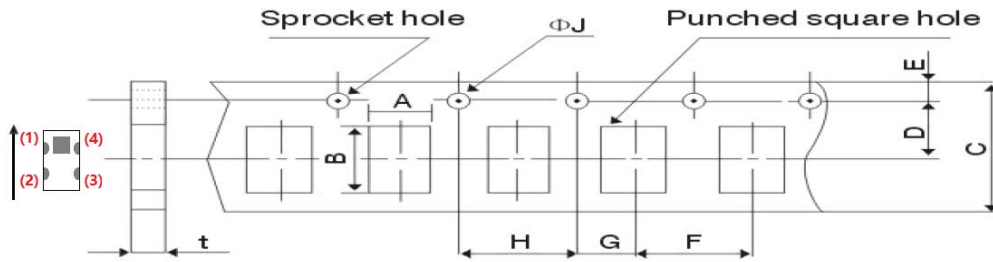
### 3、手工返工 Reworking with soldering iron

当使用电烙铁进行手工焊接时，以下条件必须严格遵守 The following conditions must be strictly followed when using a soldering iron.

预热 Pre-heating	150°C, 1 minute
尖端温度 Tip temperature	350°C max
输出功率 Soldering iron output	80w max
电烙铁头尖端尺寸 End of soldering iron	φ3mm max
焊接时间 Soldering time	3 seconds max

## 7 包装 Packaging

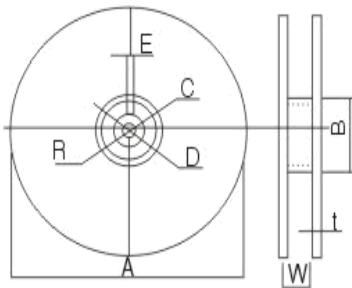
### ① 编带尺寸 Dimensions of Tape:



A	B	C	D	E	F	G	H	ΦJ	t (Max)
0.65±0.10	1.15±0.10	8.0±0.3	3.5±0.05	1.75±0.1	2.0±0.05	2.0±0.05	4.0±0.1	1.5±0.1/-0	0.8±0.05

### ② 带轮尺寸 Dimensions of Reel

Unit: mm



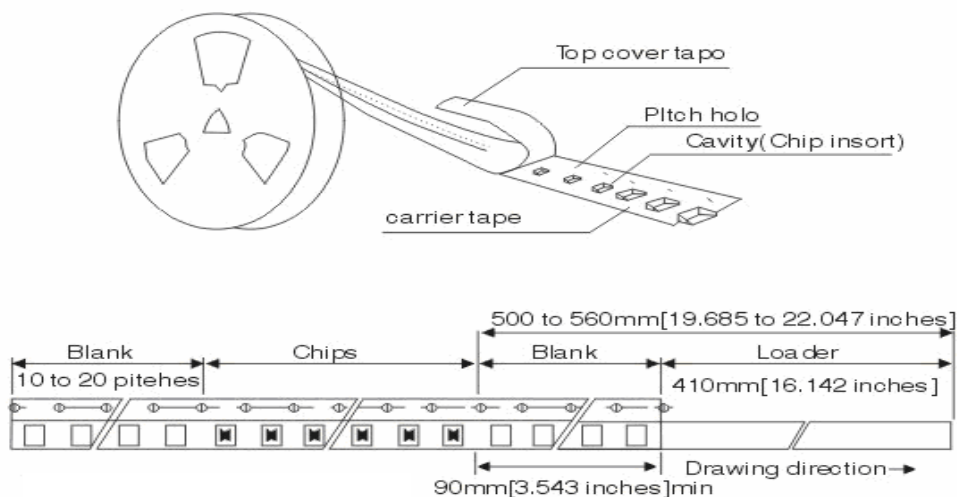
Reel material: PS (Polystyrene)

A	178±2
B	60±2
C	13.0±0.5
D	21.0±0.8
E	2.0±0.5
W	8.5±1.0
t	1.2±0.2
R	1.0±0.25

### ③ 编带抗拉强度 Pulling strength of tapes:

载带 Carrier tape	10N or more (1kgf or more)
上盖带 Cover tape	5N or more (1kgf or more)

### ④ 编带简图及拉伸方向 Taping figure and drawing direction:



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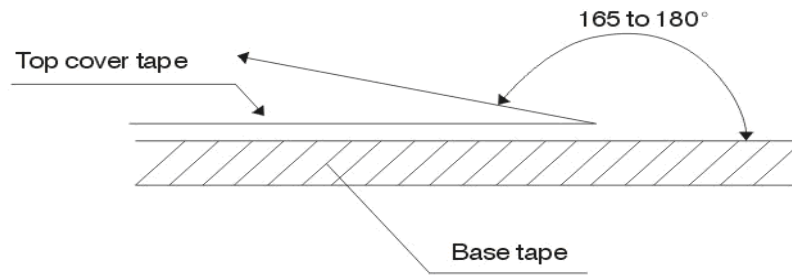
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⑤ 盖带的剥离强度 Peeling strength of cover tape:

盖带 Cover tape	0.2~0.6N (20gf~60gf)
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测试条件

- 1) 剥离角度 peel angle: 165°~180° vs. carrier tape.
- 2) 剥离速度 peel speed: 300mm/min±10%.

⑥ 包装数量 Packaging quantities: 10000 PCS / Reel